



# OL-PMCM440VNE

WLCSP4: wafer level chip-size package; 4 bumps (2 x 2)

7 June 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP4
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Package body material type</b>	X (other)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	2-7-2014
<b>Manufacturer package code</b>	WLCSP4

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.76	-	0.8	0.84	mm
E	package width	0.76	-	0.8	0.84	mm
A	seated height	0.32	-	0.35	0.38	mm
A <sub>2</sub>	package height	0.135	-	0.15	0.165	mm
e	nominal pitch	-	-	0.4	-	m
n <sub>2</sub>	actual quantity of termination	-	-	4	-	

## 2. Package outline

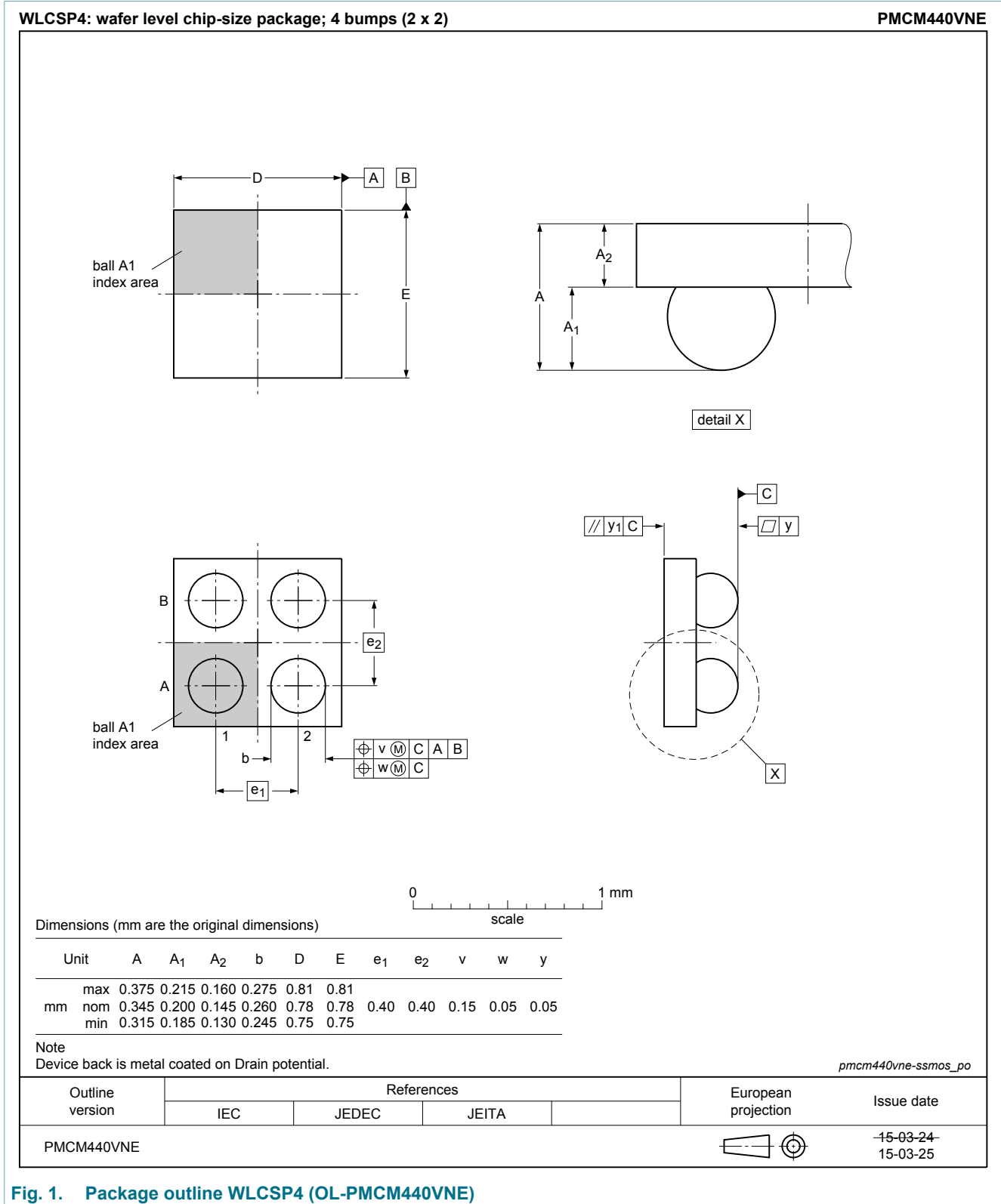
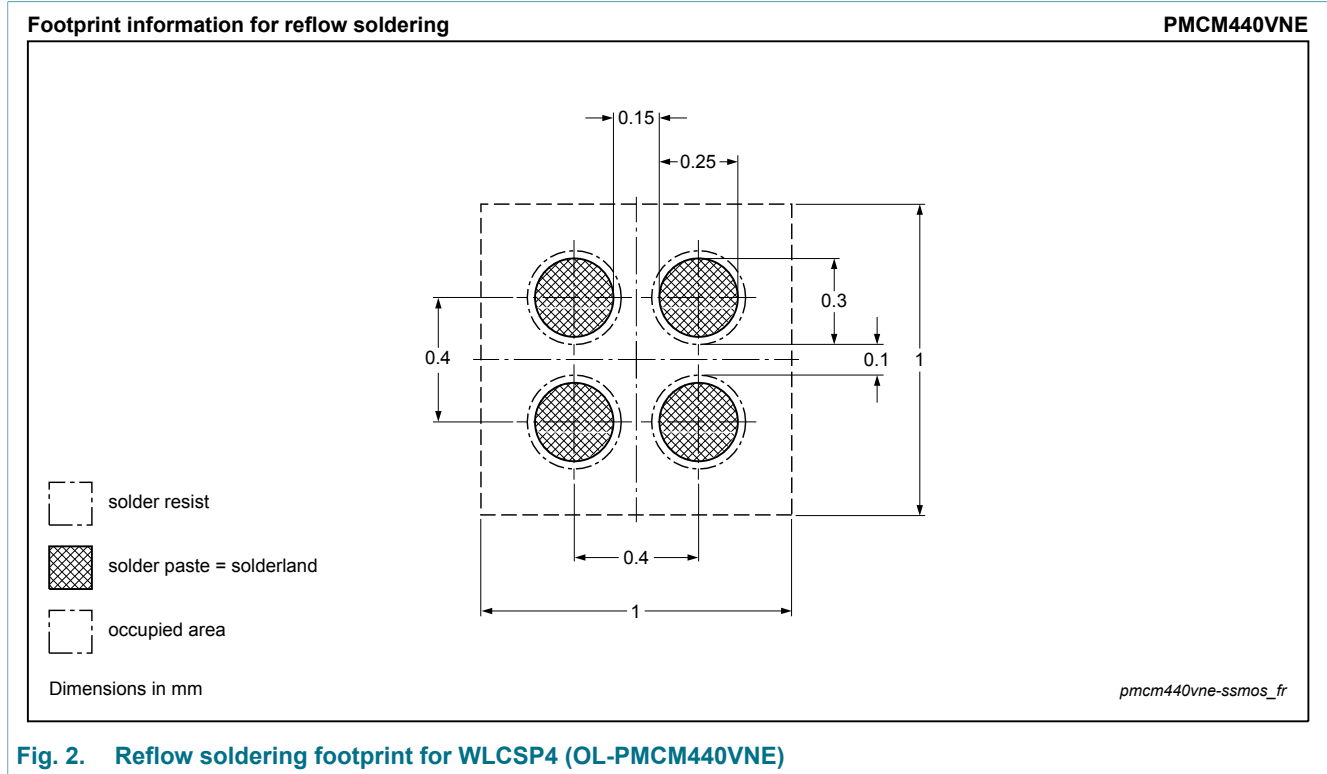


Fig. 1. Package outline WLCSP4 (OL-PMCM440VNE)

### 3. Soldering



## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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